

LIST OF REFERENCES CITED BY APPLICANT <i>(Use several sheets if necessary)</i>				ATTY. DOCKET NO.		APPLICATION NO.	
				9818-053-999		To be assigned	
				APPLICANT			
				Donald S. Fritz; SEMICONDUCTOR PACKAGE WITH STRESS INHIBITING INTERMEDIATE MOUNTING SUBSTRATE			
FILING DATE				GROUP 2827		To be assigned	
Filed Herewith							
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	TRANSLATION
							YES NO
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES NO
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)							
BV	AA	M.S. Cole, G.B. Martin, P.J. Brofman and L.S. Goldman, "CBGA Fatigue Life Improvement," <i>Proceedings of the Semiconductor Packaging Technologies Symposium</i> , Semicon West '99, Hopewell Jct., New York (1999).					
BV	AB	B.V. Fasano, R. Indyk, D. O'Connor, A.L. Plachy and S.N.S. Reddy, "Glass Ceramic Substrates for Flip Chip Packages," IBM Corporation website, at http://www.chips.ibm.com/products/interconnect/documents/swg/ (Oct. 19, 1999).					
BV	AC	R. Kuracina, "Flip Chip Packaging for the Year 2000," IBM Microelectronics, at http://www.chips.ibm.com/products/interconnect/documents/semi98/ (Oct. 19, 1999).					
BV	AD	"Ceramic Ball Grid Array (CBGA)," IBM Microelectronics, Interconnect Products, at http://www.chips.ibm.com/products/interconnect/documents/sc/cbga.html (Oct. 20, 1999).					
BV	AE	Ceramic Ball Grid Array Product Description, IBM Microelectronics, Interconnect Products at http://www.chips.ibm.com/products/interconnect/documents/sc/cga.html (Jul. 19, 2000).					
BV	AF	"Current Material (AI203) Issue," Kyocera Corporation Presentation Materials (1999).					
BV	AG	"Glass Ceramic Chip Carriers: Unleash the Power of Your Silicon With a Proven Technology, Now Available at an Affordable Price," IBM Microelectronics product brochure (1998).					
BV	AH	"µLaminate: Plastic Ball Grid Array (PBGA)," IBM Microelectronics, Interconnect Products, at http://www.chips.ibm.com/products/interconnect/documents/sc/pbga.html (Oct. 20, 1999).					
BV	AI	"Overmolded FC-BGA Package Cross Section," ASAT Presentation Materials.					
BV	AJ	"SCI: Reliability & Design Guide," NTK Communication Media Components Group, NGK Spark Plug Co., Ltd. Presentation Materials.					
BV	AK	"SolderQuik Column Grid Array (CGA)," Winslow Automation, Inc., at http://www.winslowautomation.com/cga.htm (Sept. 29, 1998).					
EXAMINER				DATE CONSIDERED			
John B. Vaughan				April 14, 2005			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

Paper No 2